

AMENDMENTS TO THE SPECIFICATION:

Please amend the paragraphs appearing at page 8, line 23 – page 9, line as follows:

Figs, 2A to 2F show processes for forming the resistor 8 in the inner hollow space of the insulator 5. First, as a center electrode installation process, the center electrode 2 is located at an axial end of the insulator 5 (refer to Fig. 2A). Then, as a first glass stuffing process, the electric conductive glass powder material is placed behind the center electrode 2 and pressed to form the glass sealing layer 8b (refer to ~~Fig. 8B~~ Fig. 2B).

Next, as a resistor stuffing process, the resistive member is located on (next to) the conductive glass powder material and pressed (~~refer to Fig. 8C~~ Fig. 2C).

Next, as a second glass stuffing process, the electric conductive glass powder material is located on (next to) the resistor 8 and pressed by the stem 7 to form the glass sealing layer 8a (~~refer to Fig. 8D~~ Fig. 2D).

Then, as shown in Fig. 3, a plurality of insulators 5 each accommodating the resistive member are placed on a metallic tray 10. Then, as a heating process, all of the insulators 5 mounted on the tray 10 are conveyed into an electric furnace (not shown) in which respective insulators 5 are heated at a predetermined sintering temperature (~~refer to Fig. 8E~~ Fig 2E).